



## Biomaterials and Biofabrication 2021

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Deadline for manuscript  
submissions:

**closed (31 December 2021)**

### Message from the Guest Editors

Dear Colleagues,

In this Special Issue, 'Biomaterials and Biofabrication 2021', with our previous successful special issue of 'Biomaterials and Biofabrication', we have started to invite new submissions exploring the up-to-date findings and research related to biofabrication (e.g., nano- and micro-fabrication and 3D bioprinting), biomaterials (e.g., decellularized extracellular matrix, conductive hydrogels, and graphene) and electronic technologies for bio/healthcare application (e.g., implantable biosensors, drug delivery systems, organoids, organ-on-a-chips, bioelectronics and wearable electronics). Communications and reviews are also welcomed.

Prof. Dr. Jangho Kim  
Prof. Dr. Seok Ho Cho  
Prof. Dr. Hee-Gyeong Yi  
*Guest Editors*





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## Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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